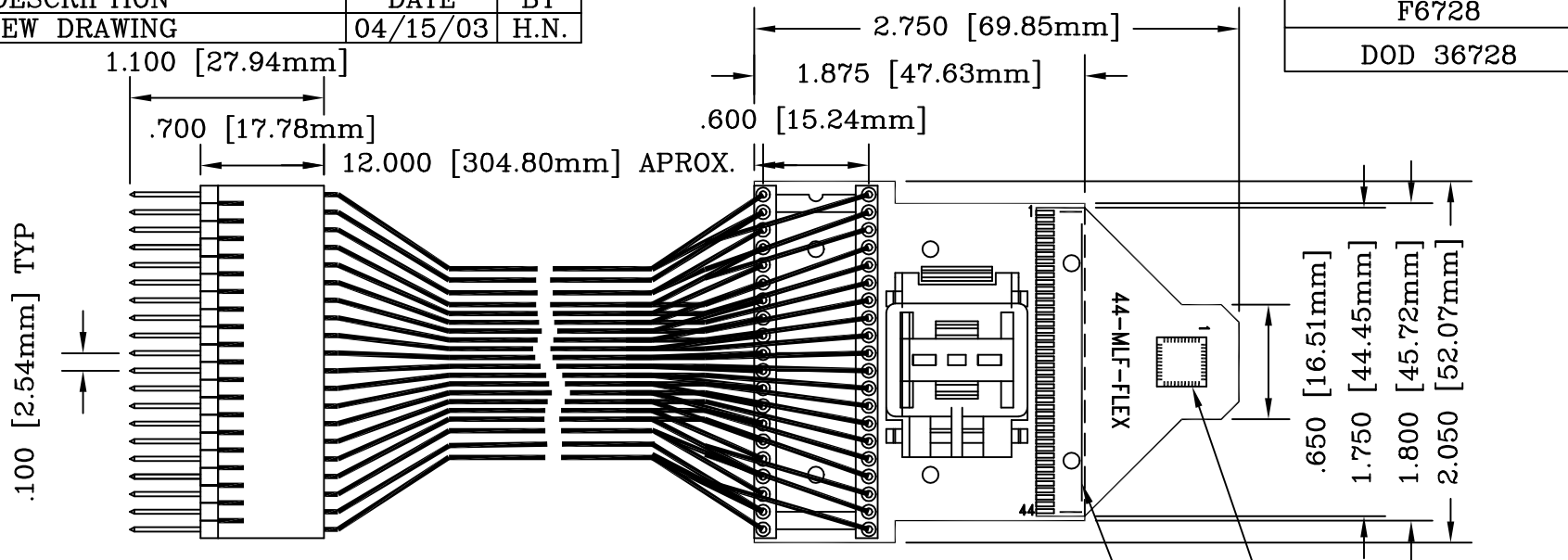
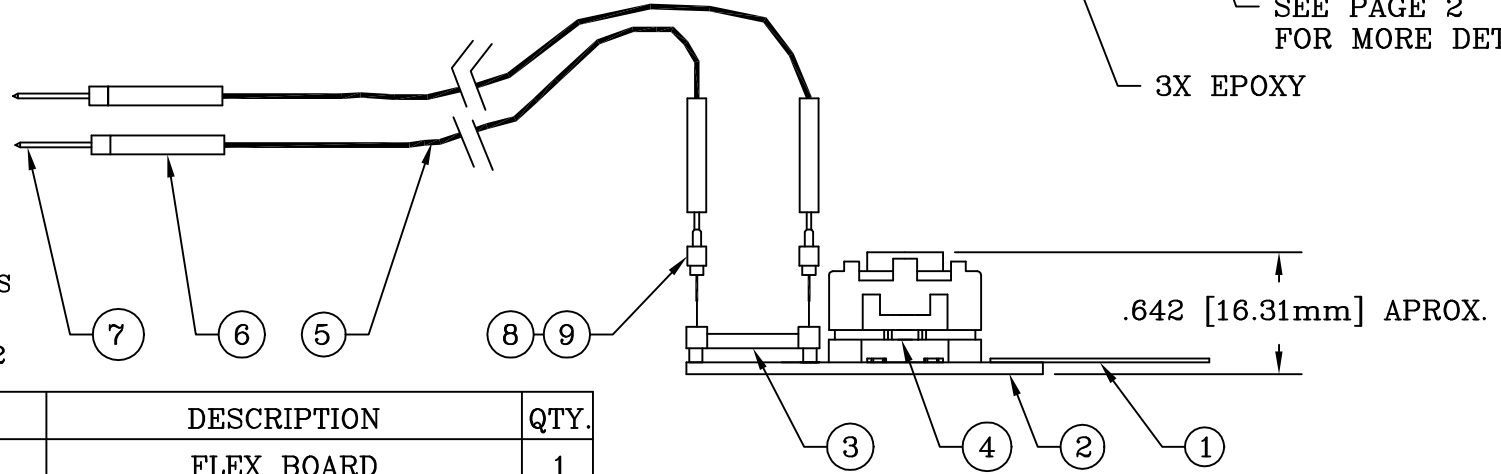


REV	DESCRIPTION	DATE	BY	F6728
A	NEW DRAWING	04/15/03	H.N.	DOD 36728



- NOTES:
1. APPLICABLE ATMEL DEVICES
MEGA16 AND MEGA32
 2. PIN OUT TABLE IN PAGE 2



NO.	ITEM	DESCRIPTION	QTY.
1	44-MLF-FLEX	FLEX BOARD	1
2	44MLF-40DIP.6	RIGID BOARD	1
3	S-DIP-00-040-A	SOLDER TOP OF # 2	1
4	S-MLF-00-044-A	SOLDER TOP OF # 2	1
5	CABLE	2 PCS OF 12 INCHES	24
6	CON-C-20-1-F	USE WITH # 5	4
7	WWPOST-36-PGA	PLUG INTO 1 SIDE # 6	2
8	HEADER-MALE-32	PLUG INTO 1 SIDE OF # 6	1
9	WWPOST-36-AS-M	SHIP WITH KIT	2

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED

Emulation Technology, Inc.
— VLSI and SMT ADAPTERS and ACCESSORIES —

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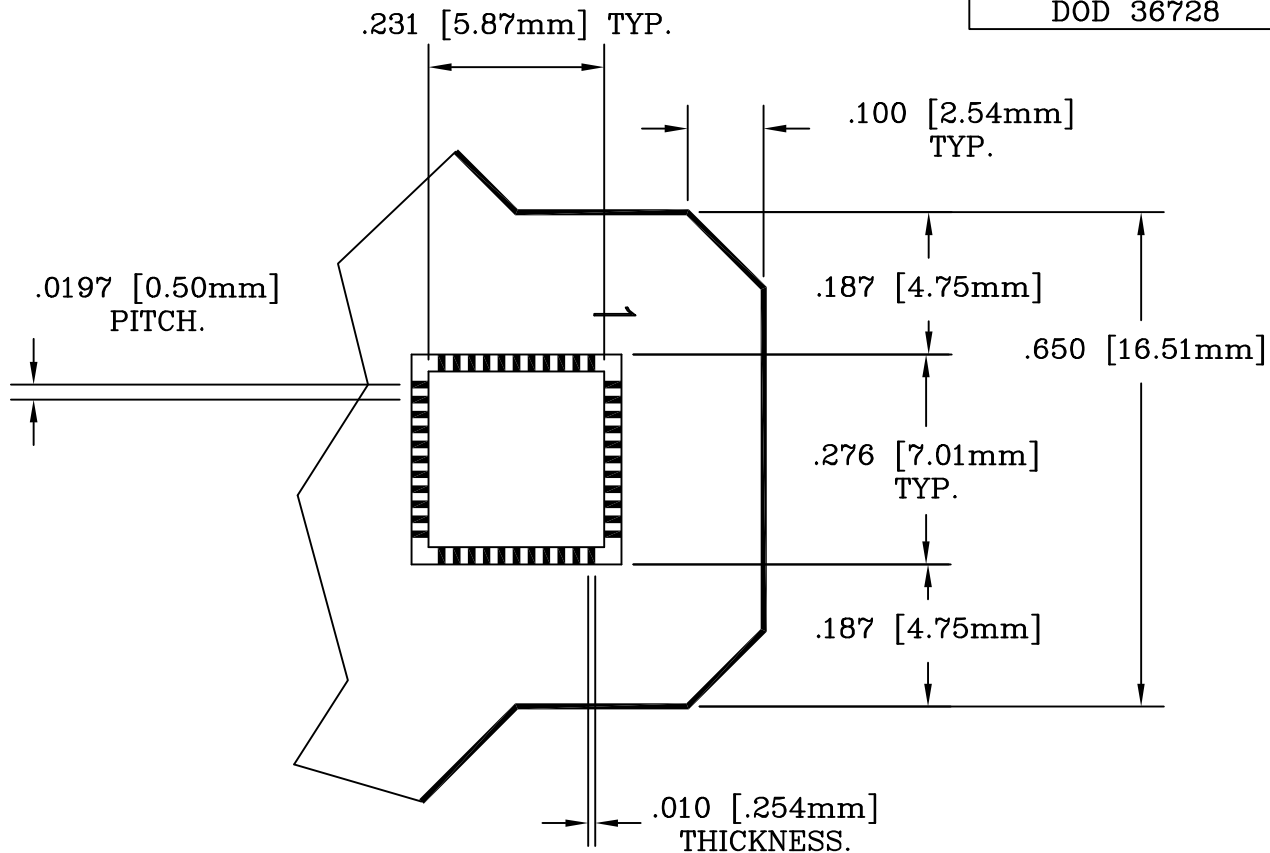
SHEET: 1 OF 2	DATE: 04/15/03	REVISION: A	ASSEMBLY DRAWING
CHECKED: Perry Munroe		DRAWN: Huy Nguyen	
Scale 1:1		DO NOT SCALE DRAWING	
ITEM: BC-X-051/S-3			DESCRIPTION: BCP-044-ML05Z-MEGA16/32-3IN1

REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	04/15/03	H.N.

F6728
DOD 36728

CONNECTION TABLE

QFP/MLF	DIP	COMMENTS
1	6	PB5
2	7	PB6
3	8	PB7
4	9	RESET
5	10	VCC
6	11	GND
7	12	XTAL2
8	13	XTAL1
9	14	PD0
10	15	PD1
11	16	PD2
12	17	PD3
13	18	PD4
14	19	PD5
15	20	PD6
16	21	PD7
17		VCC
18		GND
19	22	PC0
20	23	PC1
21	24	PC2
22	25	PC3
23	26	PC4
24	27	PC5
25	28	PC6
26	29	PC7
27	30	AVCC
28	31	NGD
29	32	AREF
30	33	PA7
31	34	PA6
32	35	PA5
33	36	PA4
34	37	PA3
35	38	PA2
36	39	PA1
37	40	PA0
38		VCC
39		GND
40	1	PB0
41	2	PB1
42	3	PB2
43	4	PB3
44	5	PB4



SCALE 4:1

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED

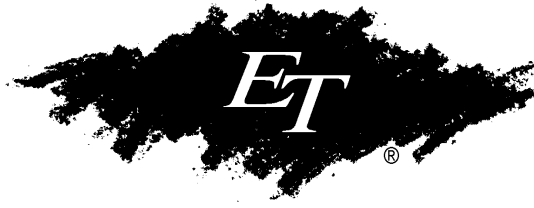


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SHEET: 2 OF 2	DATE: 04/15/03	REVISION: A	ASSEMBLY DRAWING
CHECKED: Perry Munroe	DRAWN: Huy Nguyen	ITEM: BC-X-051/S-3	
Scale 1:1	DO NOT SCALE DRAWING	DESCRIPTION: BCP-044-ML05Z-MEGA16/32-3IN1	



EMULATION TECHNOLOGY, INC.

MLF Flex Adapter User Instructions

Emulation Technology's new MLF Flex Interface Probe quickens the debug process and your time to market. This probe is multipurpose and provides signal access and instrument access to your target board. MLF Flex Interface Probe allows you to quickly and easily configure and interface to an in-circuit emulator, device programmer, logic analyzer or oscilloscope. You can change and test different chip packages, monitor performance and program MLF devices with ease and without the need of soldering MLF chip packages to your target board.

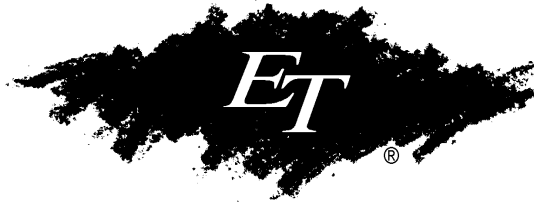
SUGGESTED SUPPLIES

63/37 or 60/40 Solder Paste
Flux paste, 10cc No-clean (ET Part# CQ291E)
Flux Remover, Chemtronics, Flux Off 2000
Tape (Masking, Scotch, etc.)

SUGGESTED EQUIPMENT

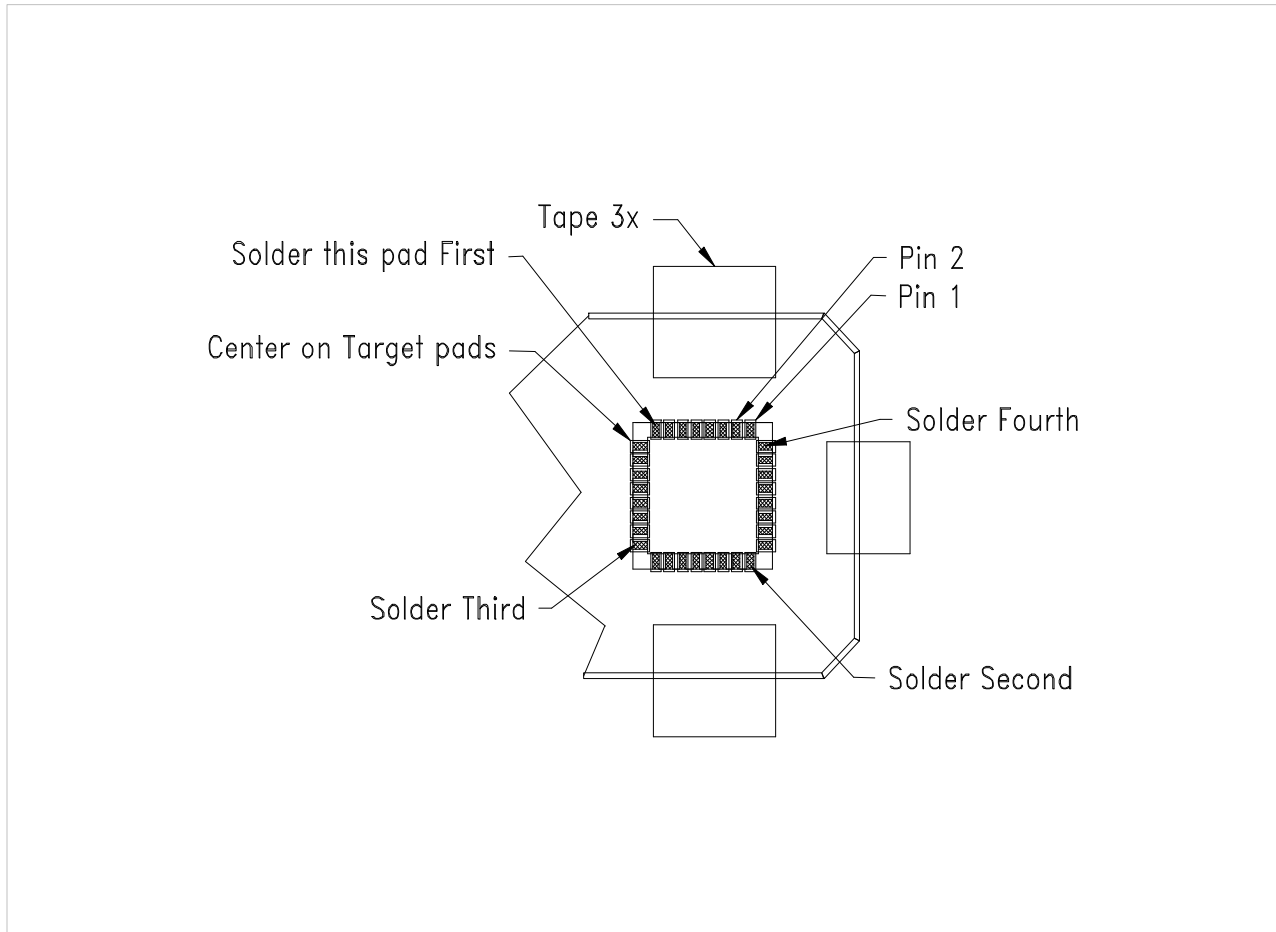
Microscope
Soldering Iron
Fine Tip for Soldering Iron

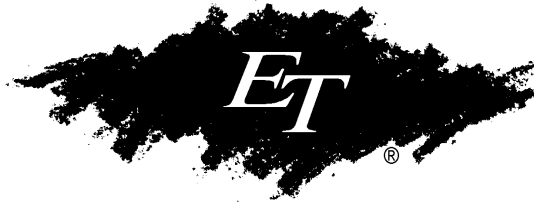
1. Under microscope, pre-tin solder pads of MLF Footprint to create consistent solder "bumps".
2. Apply liquid flux as required to the target footprint.
3. Apply 3 pieces of tape (1/4" x 1/4" sq.) to the sides of Flex Interface Probe (See Detail A for tape placement).
4. Slide Flex Interface Probe over the target footprint and align up the center of target board pads. Press down on the tape to hold in place.
5. Begin solder reflow of Flex Interface Probe to the target board pad pattern by touching the solder tip to the four corners first to secure the adapter in correct alignment, then finish the rest of pads. (See Detail A&B).
6. Clean solder joints with Flux remover.
7. Carefully configure Flex Interface Probe for emulation, programming or logic analysis.



EMULATION TECHNOLOGY, INC.

DETAIL A





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DETAIL B

